Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-09-02
Contact Name *	Refer to " Supplier Comment" section	Contact Title	Refer to " Supplier Comment" section
Contact Phone *	Refer to " Supplier Comment" section	Contact Email *	Refer to " Supplier Comment" section
Authorized Representative *	Laurent Tosi	Representative Title	MMS MD CHAMPION
Representative Phone *	(+33) 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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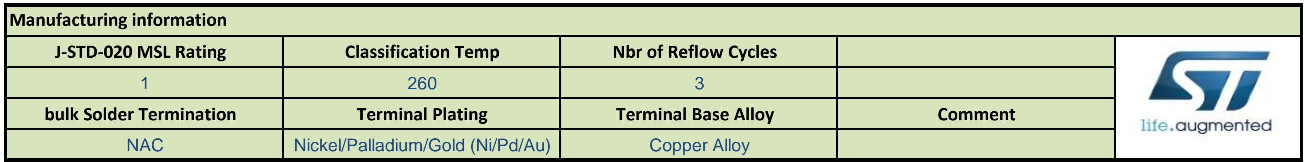
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
M95080-DRMF3TG/K	CGBM*95081KN	A	P1C7	2014-09-02
	Amount	**UoM**	**Unit type**	**ST ECOPACK Grade**
	22.00	mg	Each	ECOPACK® 2



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
1	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
QFN	2x3x0.8	8	flat	
Comment	UFDFPN 2x3x0.8 8L 0.5MM PITCH			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	**Response**
Product(s) meets EU RoHS requirement without any exemptions	**true**
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false

Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				**Response**
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**true**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CGBM*95081KN					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.509	mg	supplier	die	Silicon (Si)	7440-21-3		0.490	mg	962672	22273
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	3929	91
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	1965	45
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.016	mg	31434	727
Lead-frame	Other inorganic materials	3.272	mg	supplier	alloy	Copper (Cu)	7440-50-8		3.174	mg	970057	144288
Lead-frame				supplier	alloy	Iron (Fe)	7439-89-6		0.076	mg	23353	3474
Lead-frame				supplier	alloy	Zinc (Zn)	7440-66-6		0.004	mg	1195	178
Lead-frame				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.003	mg	836	124
Lead-frame				supplier	coating	Nickel (Ni)	7440-02-0		0.014	mg	4180	622
Lead-frame				supplier	coating	Palladium (Pd)	7440-05-3		0.001	mg	268	40
Lead-frame				supplier	coating	Gold (Au)	7440-57-5		0.000	mg	112	17
Die Attach	Other inorganic materials	0.292	mg	supplier	glue or soft solder	epoxy resin	25068-38-6		0.029	mg	100000	1328
Die Attach				supplier	glue or soft solder	Cycloaliphatic Epoxy Resin	244772-00-7		0.029	mg	100000	1328
Die Attach				supplier	glue or soft solder	Phenol resin	9003-35-4		0.029	mg	100000	1328
Die Attach				supplier	glue or soft solder	amorphous silica	7631-86-9		0.205	mg	700000	9298
Wires	Other inorganic materials	0.036	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.036	mg	1000000	1642
Encapsulation	Other inorganic materials	17.890	mg	supplier	Moulding Compound	silica vitreous	60676-86-0		15.808	mg	883587	718523
Encapsulation				supplier	Moulding Compound	Phenolic resin	Proprietary		0.792	mg	44256	35989
Encapsulation				supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.620	mg	34635	28165
Encapsulation				supplier	Moulding Compound	carbon black	1333-86-4		0.034	mg	1924	1565
Encapsulation				supplier	Moulding Compound	Zinc hydroxide	20427-58-1		0.017	mg	962	782
Encapsulation				supplier	Moulding Compound	Biphenyl epoxy resin	85954-11-6		0.620	mg	34635	28165
Finishing	Other inorganic materials	0.000	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.000	mg	916800	6
Finishing				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	0
Finishing				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0